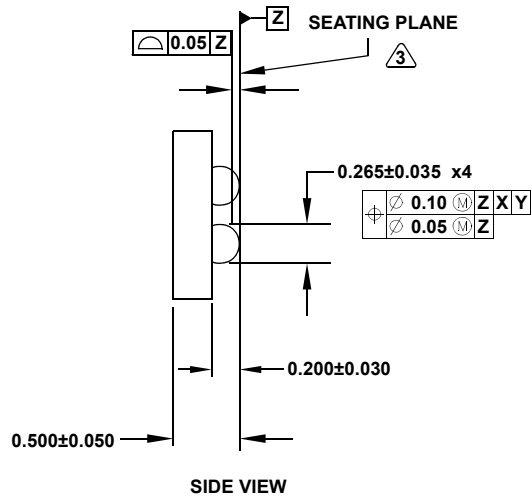
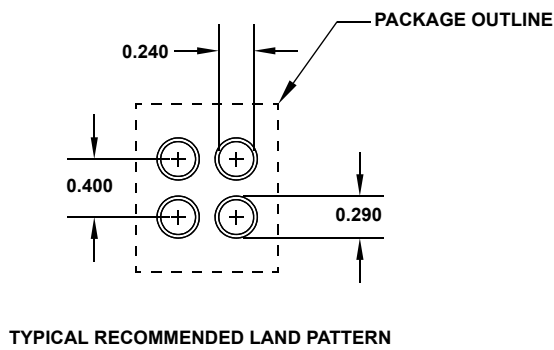
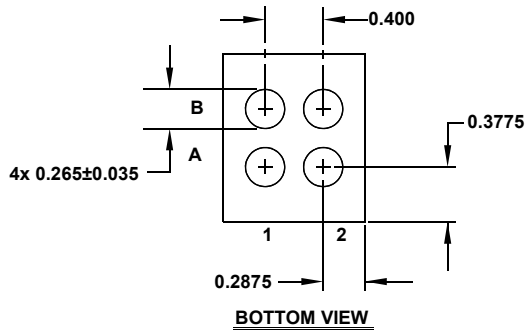
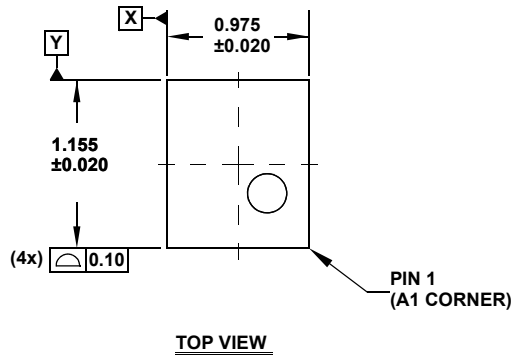


Package Outline Drawing

W2x2.4

4 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm PITCH)

Rev 3, 5/15



NOTES:

1. All dimensions are in millimeters.
2. Dimension and tolerance per ASMEY 14.5-1994 and JESD 95-1 SPP-010.
3. NSMD refers to non-solder mask defined pad design per Intersil Techbrief www.intersil.com/data/tb/tb451.pdf